

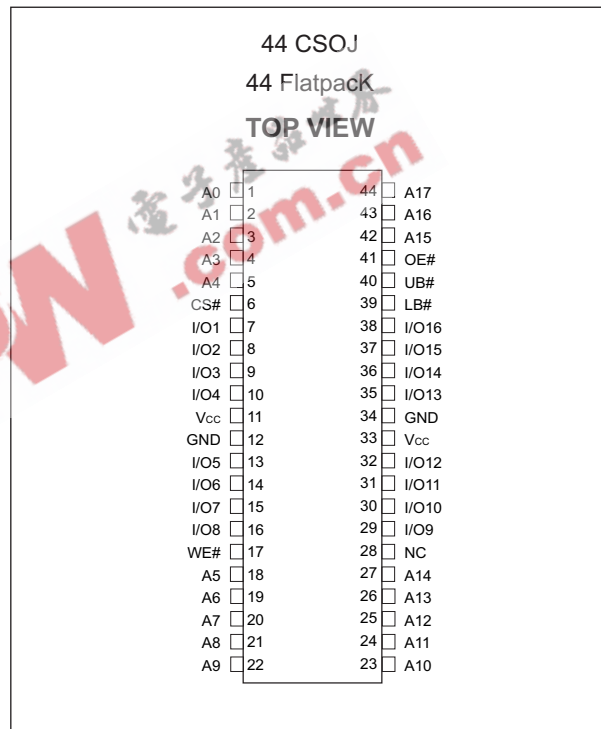


256Kx16 MONOLITHIC SRAM, SMD 5962-96902

FEATURES

- Access Times 17, 20, 25, 35ns
- MIL-STD-883 Compliant Devices Available
- Packaging
 - 44 pin Ceramic SOJ (Package 102)
 - 44 lead Ceramic Flatpack (Package 225)
 - 44 lead Formed Ceramic Flatpack
- Organized as 256Kx16
- Data Byte Control:
 - Lower Byte (LB#) = I/O₁₋₈
 - Upper Byte (UB#) = I/O₉₋₁₆
- 2V Minimum Data Retention for battery back up operation (WMS256K16L-XXX Low Power Version Only)
- Commercial, Industrial and Military Temperature Range
- 5V Power Supply
- Low Power CMOS
- TTL Compatible Inputs and Outputs

PIN CONFIGURATION FOR WMS256K16-XXX



PIN DESCRIPTION

| | |
|---------------------|---|
| A0-17 | Address Inputs |
| LB# | Lower-Byte Control (I/O ₁₋₈) |
| UB# | Upper-Byte Control (I/O ₉₋₁₆) |
| I/O ₁₋₁₆ | Data Input/Output |
| CS# | Chip Select |
| OE# | Output Enable |
| WE# | Write Enable |
| V _{CC} | +5.0V Power |
| GND | Ground |
| NC | No Connection |



TRUTH TABLE

| CS# | WE# | OE# | LB# | UB# | Mode | Data I/O | | Power |
|-----|-----|-----|-----|-----|----------------|--------------------|---------------------|---------|
| | | | | | | I/O ₁₋₈ | I/O ₉₋₁₆ | |
| H | X | X | X | X | Not Select | High Z | High Z | Standby |
| L | H | H | X | X | Output Disable | High Z | High Z | Active |
| L | X | X | H | H | | | | |
| L | H | L | L | H | Read | Data Out | High Z | Active |
| | | | H | L | | High Z | Data Out | |
| | | | L | L | | Data Out | Data Out | |
| L | L | X | L | H | Write | Data In | High Z | Active |
| | | | H | L | | High Z | Data In | |
| | | | L | L | | Data In | Data In | |

ABSOLUTE MAXIMUM RATINGS

| Parameter | Symbol | Min | Max | Unit |
|--------------------------------|------------------|------|----------------------|------|
| Operating Temperature | T _A | -55 | +125 | °C |
| Storage Temperature | T _{STG} | -65 | +150 | °C |
| Signal Voltage Relative to GND | VG | -0.5 | V _{CC} +0.5 | V |
| Junction Temperature | T _J | | 150 | °C |
| Supply Voltage | V _{CC} | -0.5 | 7.0 | V |

RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Min | Max | Unit |
|------------------------|-----------------|------|-----------------------|------|
| Supply Voltage | V _{CC} | 4.5 | 5.5 | V |
| Input High Voltage | V _{IH} | 2.2 | V _{CC} + 0.3 | V |
| Input Low Voltage | V _{IL} | -0.3 | +0.8 | V |
| Operating Temp. (Mil.) | T _A | -55 | +125 | °C |

CAPACITANCE

T_A = +25°C

| Parameter | Symbol | Condition | Max | Unit |
|--------------------|------------------|-----------------------------------|-----|------|
| Input capacitance | C _{IN} | V _{IN} = 0V, f = 1.0MHz | 20 | pF |
| Output capacitance | C _{OUT} | V _{OUT} = 0V, f = 1.0MHz | 20 | pF |

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ +125°C

| Parameter | Symbol | Conditions | Min | Max | Units |
|--------------------------|-----------------|---|-----|-----|-------|
| Input Leakage Current | I _{LI} | V _{CC} = 5.5, V _{IN} = GND to V _{CC} | | 10 | μA |
| Output Leakage Current | I _{LO} | CS# = V _{IH} , OE# = V _{IH} , V _{OUT} = GND to V _{CC} | | 10 | μA |
| Operating Supply Current | I _{CC} | CS# = V _{IL} , OE# = V _{IH} , f = 5MHz, V _{CC} = 5.5 | | 275 | mA |
| Standby Current | I _{SB} | CS# = V _{IH} , OE# = V _{IH} , f = 5MHz, V _{CC} = 5.5 | | 17 | mA |
| Output Low Voltage | V _{OL} | I _{OL} = 6mA, V _{CC} = 4.5 | | 0.4 | V |
| Output High Voltage | V _{OH} | I _{OH} = -4.0mA, V _{CC} = 4.5 | 2.4 | | V |

NOTE: DC test conditions: V_{IH} = V_{CC} - 0.3V, V_{IL} = 0.3V

LOW POWER DATA RETENTION CHARACTERISTICS (WMS256K16L-XXX ONLY)

-55°C ≤ T_A ≤ +125°C

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|-------------------------------|--------------------------------|------------------------------|-----|-----|-----|-------|
| Data Retention Supply Voltage | V _{DR} | CS# ≥ V _{CC} - 0.2V | 2.0 | | 5.5 | V |
| Data Retention Current | I _{CCDR} ¹ | V _{CC} = 3V | | 1.0 | 8.0 | mA |



AC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ +125°C

| Parameter | Symbol | -17 | | -20 | | -25 | | -35 | | Units |
|------------------------------------|-------------------------------|-----|-----|-----|-----|-----|-----|-----|-----|-------|
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| Read Cycle | | | | | | | | | | |
| Read Cycle Time | t _{RC} | 17 | | 20 | | 25 | | 35 | | ns |
| Address Access Time | t _{AA} | | 17 | | 20 | | 25 | | 35 | ns |
| Output Hold from Address Change | t _{OH} | 0 | | 0 | | 0 | | 0 | | ns |
| Chip Select Access Time | t _{ACS} | | 17 | | 20 | | 25 | | 35 | ns |
| Output Enable to Output Valid | t _{OE} | | 10 | | 12 | | 15 | | 20 | ns |
| Chip Select to Output in Low Z | t _{CLZ} ¹ | 2 | | 5 | | 5 | | 5 | | ns |
| Output Enable to Output in Low Z | t _{OLZ} ¹ | 0 | | 0 | | 0 | | 0 | | ns |
| Chip Disable to Output in High Z | t _{CHZ} ¹ | | 9 | | 10 | | 12 | | 15 | ns |
| Output Disable to Output in High Z | t _{OHZ} ¹ | | 9 | | 10 | | 12 | | 15 | ns |
| LB#, UB# Access Time | t _{BA} | | 10 | | 12 | | 14 | | 17 | ns |
| LB#, UB# Enable to Low Z Output | t _{BLZ} ¹ | 0 | | 0 | | 0 | | 0 | | ns |
| LB#, UB# Disable to High Z Output | t _{BHZ} ¹ | | 9 | | 10 | | 12 | | 15 | ns |

1. This parameter is guaranteed by design but not tested.

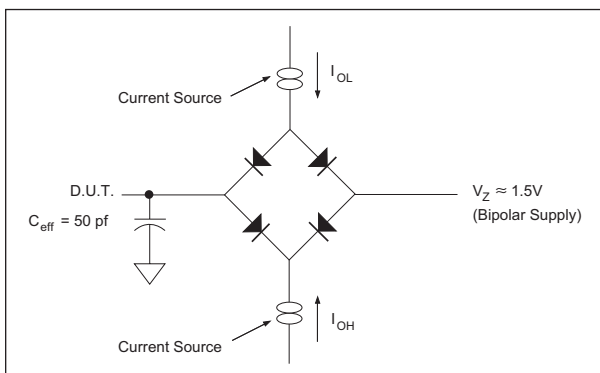
AC CHARACTERISTICS

V_{CC} = 5.0V, GND = 0V, -55°C ≤ T_A ≤ +125°C

| Parameter | Symbol | -17 | | -20 | | -25 | | -35 | | Units |
|----------------------------------|-------------------------------|-----|-----|-----|-----|-----|-----|-----|-----|-------|
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| Write Cycle | | | | | | | | | | |
| Write Cycle Time | t _{WC} | 17 | | 20 | | 25 | | 35 | | ns |
| Chip Select to End of Write | t _{CW} | 14 | | 17 | | 20 | | 25 | | ns |
| Address Valid to End of Write | t _{AW} | 14 | | 17 | | 20 | | 25 | | ns |
| Data Valid to End of Write | t _{DW} | 10 | | 12 | | 15 | | 20 | | ns |
| Write Pulse Width | t _{WP} | 14 | | 17 | | 20 | | 25 | | ns |
| Address Setup Time | t _{AS} | 0 | | 0 | | 0 | | 0 | | ns |
| Address Hold Time | t _{AH} | 2 | | 2 | | 2 | | 2 | | ns |
| Output Active from End of Write | t _{OW} ¹ | 0 | | 0 | | 0 | | 0 | | ns |
| Write Enable to Output in High Z | t _{WHZ} ¹ | | 9 | | 10 | | 10 | | 15 | ns |
| Data Hold Time | t _{DH} | 0 | | 0 | | 0 | | 0 | | ns |
| LB#, UB# Valid to End of Write | t _{BW} | 14 | | 17 | | 20 | | 25 | | ns |

1. This parameter is guaranteed by design but not tested.

AC TEST CIRCUIT



AC TEST CONDITIONS

| Parameter | Typ | Unit |
|----------------------------------|--|------|
| Input Pulse Levels | V _{IL} = 0, V _{IH} = 3.0 | V |
| Input Rise and Fall | 5 | ns |
| Input and Output Reference Level | 1.5 | V |
| Output Timing Reference Level | 1.5 | V |

Notes:

V_Z is programmable from -2V to +7V.

I_{OL} & I_{OH} programmable from 0 to 16mA.

Tester Impedance Z₀ = 75 Ω.

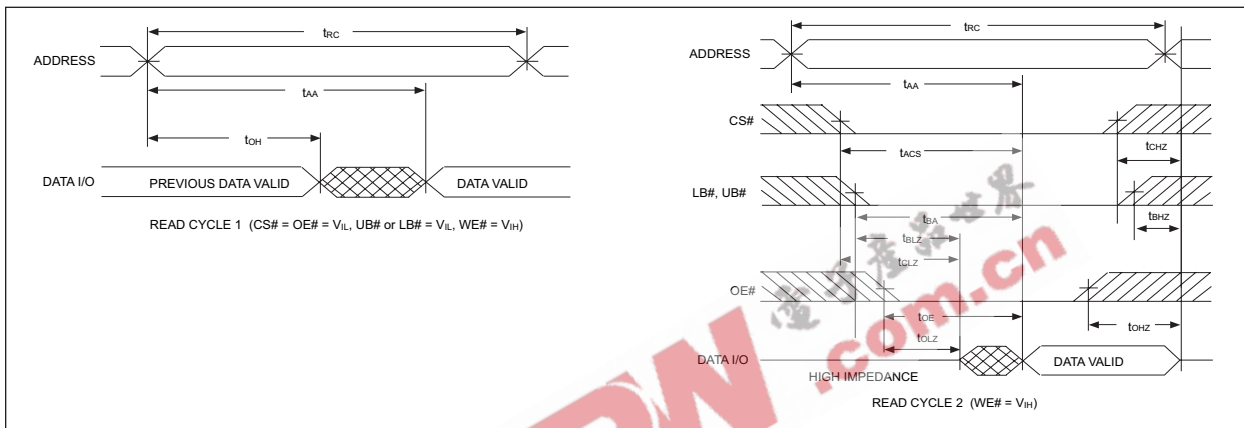
V_Z is typically the midpoint of V_{OH} and V_{OL}.

I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.

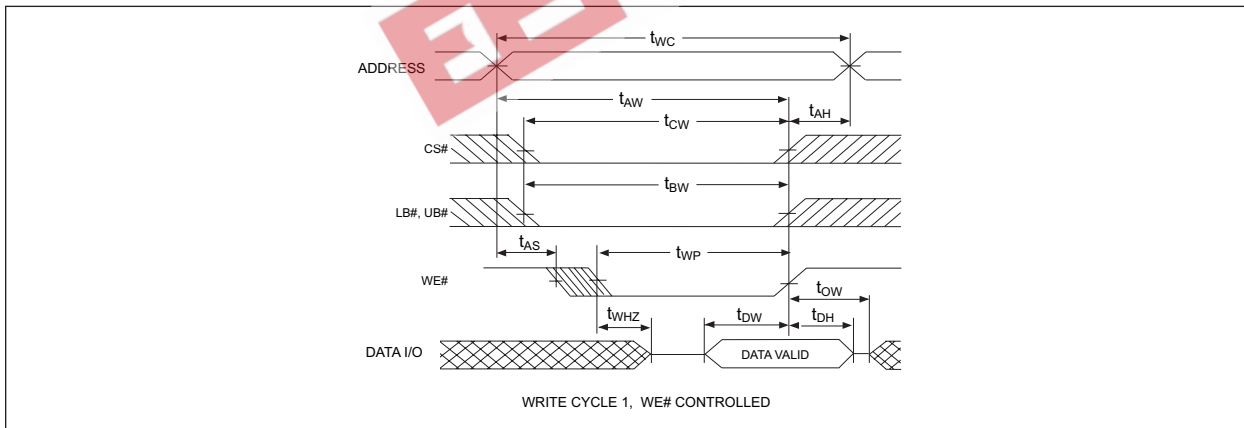
ATE tester includes jig capacitance.



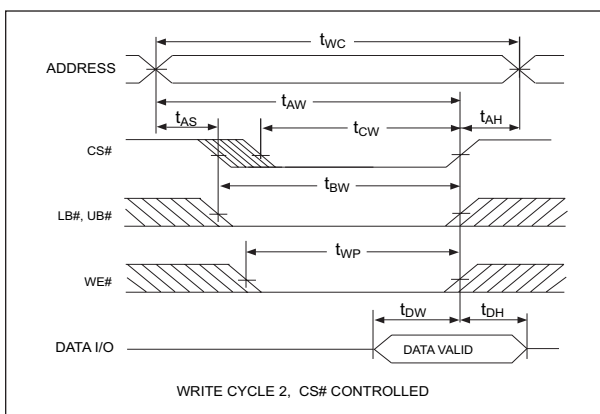
TIMING WAVEFORM - READ CYCLE



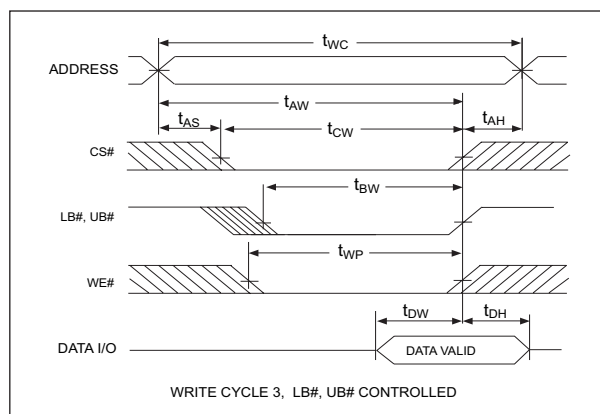
WRITE CYCLE - WE# CONTROLLED



WRITE CYCLE - CS# CONTROLLED

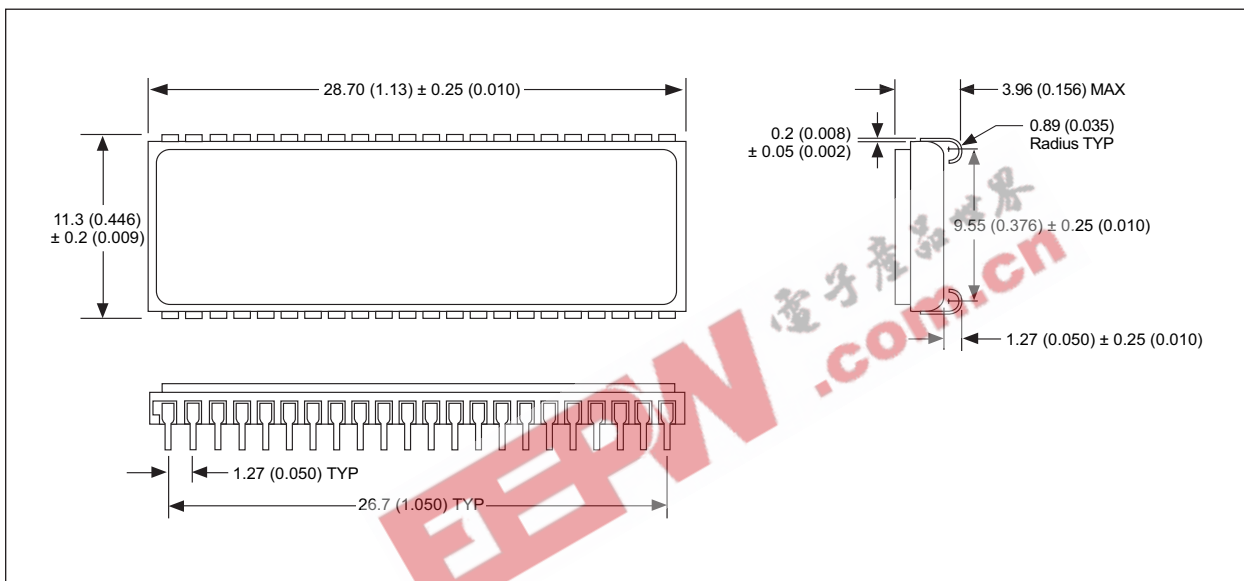


WRITE CYCLE - LB#, UB# CONTROLLED



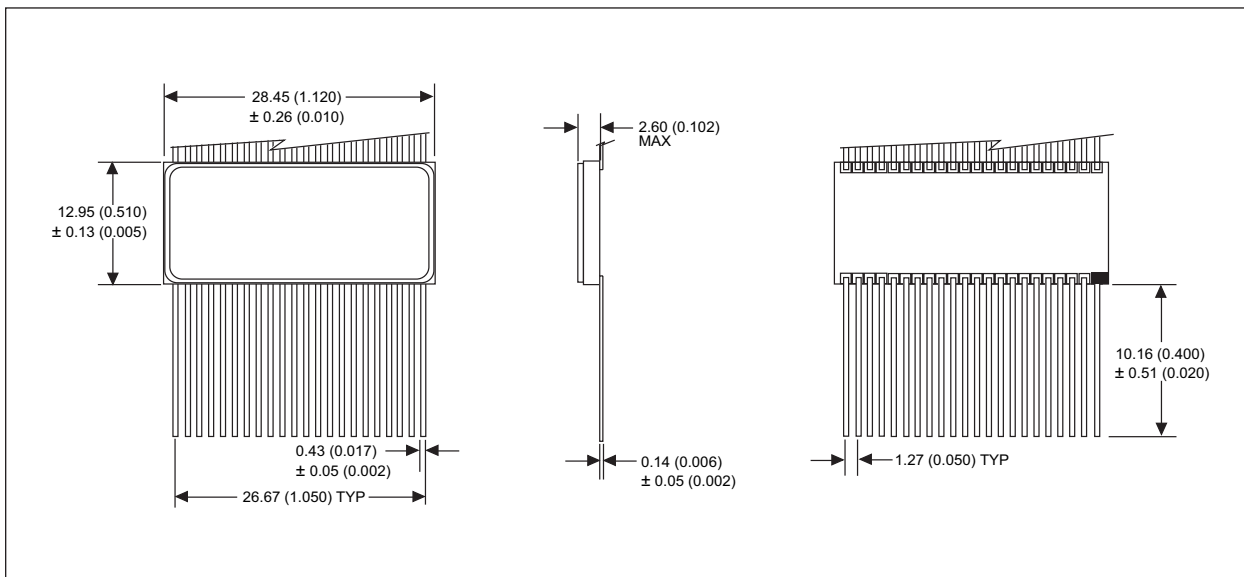


PACKAGE 102: 44 LEAD, CERAMIC SOJ



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

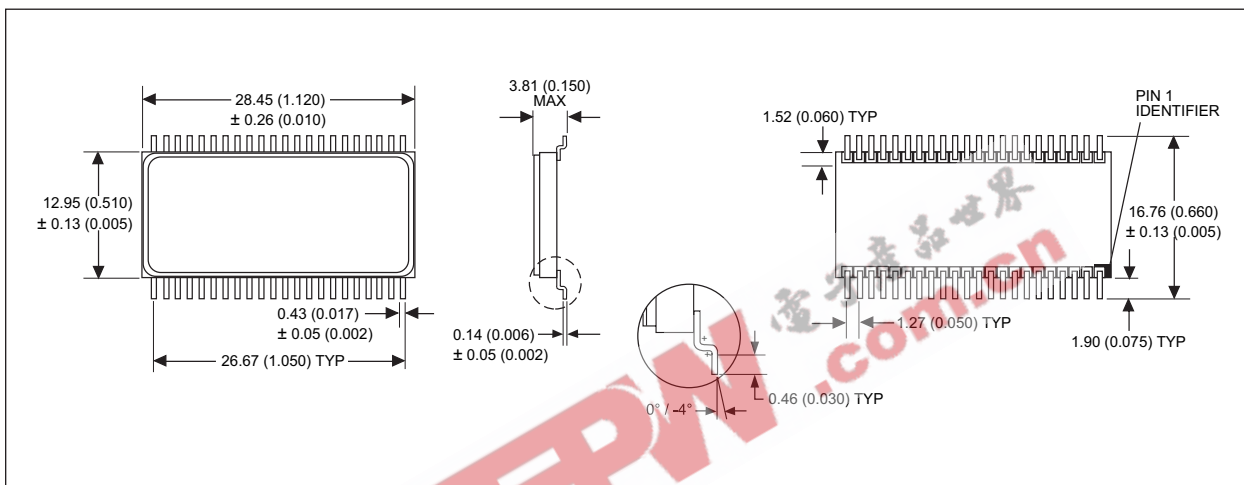
PACKAGE 225: 44 LEAD, CERAMIC FLAT PACK



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



PACKAGE 211: 44 LEAD FORMED, CERAMIC FLAT PACK



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

ORDERING INFORMATION

W M S 256K16 X - XXX X X X

LEAD FINISH:

- Blank = Gold plated leads
- A = Solder dip leads

DEVICE GRADE:

- M = Military Screened -55°C to +125°C
- I = Industrial -40°C to +85°C
- C = Commercial 0°C to +70°C

PACKAGE:

- DL = 44 Lead Ceramic SOJ (Package 102)
- FL = 44 Lead Ceramic Flatpack (Package 225)
- FG = 44 Lead Formed Ceramic Flatpack

ACCESS TIME (ns)

IMPROVEMENT MARK:

- Blank = Standard Power
- L = Low Power Data Retention

ORGANIZATION, 256K x 16

SRAM

MONOLITHIC

WHITE ELECTRONIC DESIGNS CORP.



| DEVICE TYPE | SPEED | PACKAGE | SMD NO. |
|---------------------------|-------|------------------------------|------------------|
| 256K x 16 SRAM Monolithic | 35ns | 44 lead SOJ (DL) | 5962-96902 01HMX |
| 256K x 16 SRAM Monolithic | 25ns | 44 lead SOJ (DL) | 5962-96902 02HMX |
| 256K x 16 SRAM Monolithic | 20ns | 44 lead SOJ (DL) | 5962-96902 03HMX |
| 256K x 16 SRAM Monolithic | 17ns | 44 lead SOJ (DL) | 5962-96902 04HMX |
| 256K x 16 SRAM Monolithic | 35ns | 44 lead Flatpack (FL) | 5962-96902 01HNX |
| 256K x 16 SRAM Monolithic | 25ns | 44 lead Flatpack (FL) | 5962-96902 02HNX |
| 256K x 16 SRAM Monolithic | 20ns | 44 lead Flatpack (FL) | 5962-96902 03HNX |
| 256K x 16 SRAM Monolithic | 17ns | 44 lead Flatpack (FL) | 5962-96902 04HNX |
| 256K x 16 SRAM Monolithic | 35ns | 44 lead Formed Flatpack (FG) | 5962-96902 01HTX |
| 256K x 16 SRAM Monolithic | 25ns | 44 lead Formed Flatpack (FG) | 5962-96902 02HTX |
| 256K x 16 SRAM Monolithic | 20ns | 44 lead Formed Flatpack (FG) | 5962-96902 03HTX |
| 256K x 16 SRAM Monolithic | 17ns | 44 lead Formed Flatpack (FG) | 5962-96902 04HTX |